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North America: Emerson & Cuming, 46 Manning Road, Billerica, MA 01821 U.S.A. Tel: 1-978-436-9700 Toll Free: 1-800-832-4929 Fax: 1-978-436-9701
Europe: Nijverheidsstraat 7, B-2260 Westerlo, Belgium Tel: +32 (0) 14 57 56 11 Fax: +32 (0) 14 58 55 30 E-mail: emerson.cuming@innet.be
Asia-Pacific: 100 Kaneda, Atsugi-shi, Kanagawa-ken, 243 Japan Tel: +81 462-25-8815 Fax: +81 462-22-1347
China: No. 332 Meigui South Road, WaiGaoQiao Free Trade Zone, Shanghai 200131, P.R. China Tel: (8621) 38984800 Fax: (8621) 50484160
Korea : 3rd Fl, Green Tower Building, 1617-34, Seocho-dong, Seocho-gu, Seoul 137-877, Tel (82)-2-3471-5675, Fax (82)-2-3471-5674
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SELECTOR GUIDE

DIELECTRIC ADHESIVES

ELECTRICALLY CONDUCTIVE ADHESIVES - CIRCUIT ASSEMBLY ADHESIVES

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SELECTOR GUIDE

Product	Chemistry	Composition	Viscosity at 25°C (Pa.s)	Recommended Cure Schedule(s)	Tensile Lap Shear Strength (MPa) Typical Value	Thermal Conductivity (W/m.K)	Service Temperature	Features
General Purpose Adhesives								
ECCOBOND™ 24	Epoxy	A + B	0,6 - 1,0	16 to 24 hours @ RT	12	0,2	-45 to +90°C	Low viscosity, clear transparent epoxy adhesive.
ECCOBOND 45 W 1	Epoxy	A + B	Part A : 200 - 250 Part B : 20 - 40	8 hours @ RT or 30 minutes @ 70°C	30[1]	-	-55 to +90°C	Two component, room temperature curing epoxy adhesive with variable flexibility. Designed for use where shock and peel resistance are desired.
ECCOBOND 104	Epoxy	A + B	Paste	3 hours @ 150°C or 1 hour @ 200°C	11	0,45	-45 to +230°C	Two component, epoxy adhesive which exhibits outstanding physical and dielectric properties up to 230°C.
ECCOBOND 144 A	Epoxy	One Component	75 - 110	4 hours @ 80°C or 30 minutes @ 150°C	15	0,6	-60 to +200°C	One component epoxy adhesive with fast cure at elevated temperatures.
ECCOBOND A 401-12	Epoxy	One Component	35 - 50	1 hour @ 120°C or 5 minutes @ 180°C	12	0,55	-45 to +150°C	One component, high strength, solventless, fast curing epoxy adhesive.
ECCOBOND 2332	Epoxy	One Component	65 - 85	90 minutes @ 100°C or 20 minutes @ 150°C	22	-	-45 to +150°C	One component, slightly thixotropic, solventless epoxy adhesive with high peel and tensile strength when cured at temperatures as low as 100°C.
ECCOBOND 50126 FC	Epoxy	A + B	Part A : 10 - 15 Part B : 13 - 18	6 minutes @ RT	25	0,2	-45 to +100°C	Epoxy adhesive with very fast cure at room temperature.
Thermally Conductive Adhesives								
ECCOBOND 282	Epoxy	One Component	# 7 @ 10 rpm : 280 - 380	4 hours @ 100°C or 30 minutes @ 150°C	17	1,2	-20 to +175°C	One component, screen printable epoxy adhesive with high thermal conductivity.
ECCOBOND 285	Epoxy	A + B	Paste	24 hours @ RT with Catalyst 9 2 hours @ 120°C with Catalyst 27-1 24 hours @ RT with Catalyst 24 LV	9 9 10	1,3 1,2 1,1	-45 to +120°C -45 to +180°C -45 to +90°C	Two component, thixotropic, thermally conductive, general purpose adhesive. Produces a rigid, high strength bond to most materials including metals, glass, ceramics and most plastics.
ECCOBOND E 3503-1	Epoxy	One Component	30 - 40	30 minutes @ 100°C or 5 minutes @ 150°C	8	1,0	-45 to +150°C	One component, low temperature curing, thermally conductive adhesive.
ECCOBOND E 8502-1	Modified Epoxy	One Component	40 - 50	90 minutes @ 120°C or 15 minutes @ 175°C	3	1,0	-45 to +200°C	One component, low stress adhesive for mismatched CTE applications.
UV Curing Adhesive								
ECCOBOND UV 9110	UV Acrylate	One Component	# 3 @ 10 rpm : 2	3 - 8 seconds[2]	6	0,2	-45 to +120°C	One component, UV and visible light curing adhesive providing superior adhesion and flexibility.

[1] 150 A to 100 B ratio

[2] 80 W/cm medium pressure mercury vapour lamp

Product	Chemistry	Colour	Viscosity at 25°C (Pa.s)	Recommended Cure Schedule	Application Method			Tensile Lap Shear Strength (MPa) Typical Value	Service Temperature	Features
					Dispensing	Printing	Pin Transfer			
Surface Mount Adhesives										
ECCOBOND D 125 F	Epoxy	yellow or dark red	30 - 44	2,5 minutes @ 120°C[3]	•	•	•	7	-40 to +120°C	Low exotherm, low water absorption. High hot strength. High speed dispensing without stringing.
ECCOBOND D 125 F 3	Epoxy	yellow	45 - 75	2,5 minutes @ 120°C[3]	•	•	•	8	-40 to +120°C	Low exotherm, low water absorption. High hot strength. Extreme green strength.
ECCOBOND D 125 F 5	Epoxy	yellow	# TF @ 5 rpm : 2500 - 2600	2,5 minutes @ 120°C[3]	•	•		6	-40 to +120°C	Low exotherm, low water absorption. High hot strength. Extreme green strength.
ECCOBOND E 6752	Epoxy	fluorescent red	# TF @ 5 rpm : 1000	3,5 minutes @ 120°C[3]	•			14	-40 to +105°C	Designed specifically for use in high speed pneumatic and positive displacement dispensers ; 50.000 dots/hour.

[3] IR or convection conveyor oven